

P-Channel Enhancement Mode MOSFET Feature

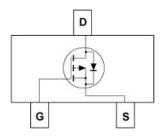
• -20V/-3A, $R_{DS(ON)} = 125 m \Omega(MAX) \ @V_{GS} = -4.5 V.$ $R_{DS(ON)} = 140 m \Omega(MAX) \ @V_{GS} = -2.5 V.$

- Super High dense cell design for extremely low RDS(ON)
- Reliable and Rugged
- SOT-23 for Surface Mount Package



Applications

- Power Management
- Portable Equipment and Battery Powered Systems.



Absolute Maximum Ratings

TA=25°C Unless Otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$ m V_{DS}$	-20	V
Gate-Source Voltage	V_{GS}	±10	V
Drain Current-Continuous	I_D	-3	A

Electrical Characteristics

Ta=25°C Unless Otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
Off Characteristics	- 25		33		888	153
Drain to Source Breakdown Voltage	BVDSS	VGS=0V, ID=-250μA	-20	2	-	V
Zero-Gate Voltage Drain Current	IDSS	VDS=-20V, VGS=0V	-	-	-1	μА
Gate Body Leakage Current, Forward	IGSSF	VGS=10V, VDS=0V	-	-	100	nA
Gate Body Leakage Current, Reverse	IGSSR	VGS=-10V, VDS=0V	-	-	-100	nA
On Characteristics			•	•		•
Gate Threshold Voltage	VGS(th)	VGS= VDS, ID=-250µA	-0.4	-	-1.0	V
Static Drain-source	RDS(ON)	VGS =-4.5V, ID =-3.0A	-		120	mΩ
On-Resistance		VGS =-2.5V, ID =-2.0A	1050	-	150	mΩ
Drain-Source Diode Characterist	ics and Maximum I	Ratings				
Drain-Source Diode Forward Voltage	VSD	VGS =0V, IS=-1.25A			-1.2	V

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Typical Characteristics

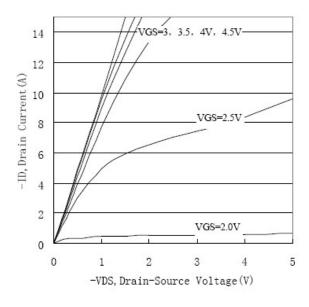


Figure 1. Output Characteristics

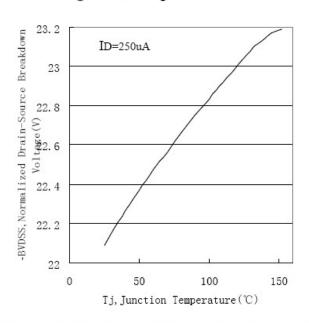


Figure 3. Breakdown Voltage Variation with Temperature

Figure 2. Transfer Characteristics

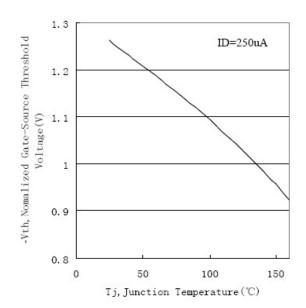
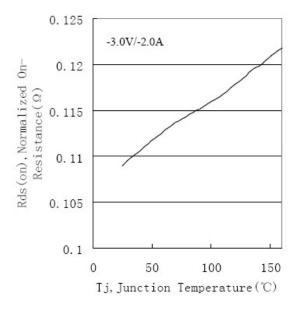


Figure 4. Gate Threshold Variation with Temperature

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Typical Characteristics



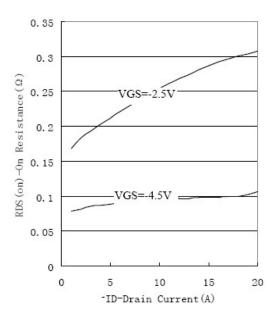
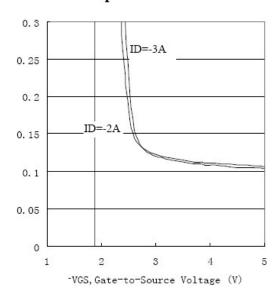


Figure 5. On-Resistance Variation with Temperature

Figure 6. On-Resistance vs. Drain Current



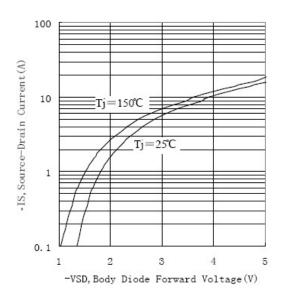


Figure 7. On-Resistance vs. Gate-to-Source Voltage Voltage

Figure 8. Source-Drain Diode Forward



Package Outline Dimensions (UNIT: mm)

SOT-23

